

Title (en)

METHOD FOR PRODUCING A SENSOR SYSTEM AND SENSOR SYSTEM

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES SENSORSYSTEMS UND SENSORSYSTEM

Title (fr)

PROCEDE DE FABRICATION D'UN SYSTEME CAPTEUR ET SYSTEME CAPTEUR AINSI OBTENU

Publication

**EP 2118629 A2 20091118 (DE)**

Application

**EP 08700276 A 20080115**

Priority

- AT 2008000009 W 20080115
- AT 722007 A 20070115
- AT 1932007 A 20070206

Abstract (en)

[origin: WO2008086551A2] The invention relates to a method for producing a sensor system for monitoring elements (1) by measurement, in particular supporting frame elements, comprising at least one sensor (5) using thick-layer technology with a line (8) for connection to a measurement system, wherein the at least one sensor (5) is constituted by at least one layer of an electrically conductive paste (2) which is baked. The aim of the invention is to create a method and sensor system in which elements (1) which would not fit into a continuous furnace could be provided with sensors (5) using thick-layer technology. To this end, the at least one sensor (5) is arranged directly on the surface of the element to be monitored (1), while the at least one layer of the paste (2) for the formation of the at least one sensor (5), and eventually for the formation of connecting lines (8) and a field bus, is applied directly onto the surface of the element to be monitored (1) and directly baked onto said element (1).

IPC 8 full level

**G01L 1/00** (2006.01)

CPC (source: EP US)

**G01L 1/2293** (2013.01 - EP US)

Citation (search report)

See references of WO 2008086551A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)

**WO 2008086551 A2 20080724; WO 2008086551 A3 20080904**; CN 101675328 A 20100317; EP 2118629 A2 20091118; US 2010284130 A1 20101111; US 8505379 B2 20130813

DOCDB simple family (application)

**AT 2008000009 W 20080115**; CN 200880008390 A 20080115; EP 08700276 A 20080115; US 44890108 A 20080115